

V_{DRM}	=	5200 V
$I_{T(AV)M}$	=	1975 A
$I_{T(RMS)}$	=	3100 A
I_{TSM}	=	29×10^3 A
V_{TO}	=	1.02 V
r_T	=	0.32 mΩ

Phase Control Thyristor

5STP 17H5200

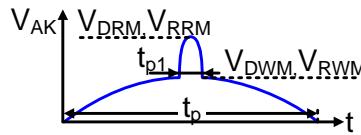
Doc. No. 5SYA1049-04 Jan. 11

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

Blocking

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	5STP 17H5200		Unit
Max. surge peak forward and reverse blocking voltage	V_{DSM}, V_{RSM}	$t_p = 10$ ms, $f = 5$ Hz $T_{vj} = 5 \dots 125^\circ\text{C}$, Note 1	5200		V
Max repetitive peak forward and reverse blocking voltage	V_{DRM}, V_{RRM}	$f = 50$ Hz, $t_p = 10$ ms, $t_{p1} = 250$ μs, $T_{vj} = 5 \dots 125^\circ\text{C}$, Note 1, Note 2	5200		V
Max crest working forward and reverse voltages	V_{DWM}, V_{RWM}	V_{AK}	3470		V
Critical rate of rise of commutating voltage	dv/dt_{crit}	Exp. to 3470 V, $T_{vj} = 125^\circ\text{C}$	2000		V/μs



Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	I_{DRM}	$V_{DRM}, T_{vj} = 125^\circ\text{C}$			400	mA
Reverse leakage current	I_{RRM}	$V_{RRM}, T_{vj} = 125^\circ\text{C}$			400	mA

Note 1: Voltage de-rating factor of 0.11% per °C is applicable for T_{vj} below +5 °C

Note 2: Recommended minimum ratio of V_{DRM} / V_{DWM} or $V_{RRM} / V_{RWM} = 2$. See App. Note 5SYA 2051.

Mechanical data

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		45	50	60	kN
Acceleration	a	Device unclamped			50	m/s ²
Acceleration	a	Device clamped			100	m/s ²

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				0.9	kg
Housing thickness	H	$F_M = 50$ kN, $T_a = 25^\circ\text{C}$	26.2		26.8	mm
Surface creepage distance	D_S		36			mm
Air strike distance	D_a		15			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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On-state

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	$I_{T(AV)M}$	Half sine wave, $T_c = 70^\circ C$			1975	A
RMS on-state current	$I_{T(RMS)}$				3100	A
Peak non-repetitive surge current	I_{TSM}	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C, \text{sine wave}$ $\text{after surge: } V_D = V_R = 0 \text{ V}$			29×10^3	A
Limiting load integral	I^2t				4.21×10^6	$A^2\text{s}$
Peak non-repetitive surge current	I_{TSM}	$t_p = 8.3 \text{ ms}, T_{vj} = 125^\circ C, \text{sine wave}$ $\text{after surge: } V_D = V_R = 0 \text{ V}$			31×10^3	A
Limiting load integral	I^2t				3.99×10^6	$A^2\text{s}$

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V_T	$I_T = 2000 \text{ A}, T_{vj} = 125^\circ C$			1.68	V
Threshold voltage	$V_{(TO)}$	$I_T = 1000 \text{ A} - 3000 \text{ A}, T_{vj} = 125^\circ C$			1.02	V
Slope resistance	r_T				0.32	$m\Omega$
Holding current	I_H	$T_{vj} = 25^\circ C$			80	mA
		$T_{vj} = 125^\circ C$			60	mA
Latching current	I_L	$T_{vj} = 25^\circ C$			600	mA
		$T_{vj} = 125^\circ C$			200	mA

Switching

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	di/dt_{crit}	$T_{vj} = 125^\circ C, I_{TRM} = 3000 \text{ A}, f = 50 \text{ Hz}$			200	$A/\mu s$
Critical rate of rise of on-state current	di/dt_{crit}	$V_D \leq 0.67 V_{DRM}, I_{FG} = 2 \text{ A}, t_r = 0.5 \mu s$			1000	$A/\mu s$
Circuit-commutated turn-off time	t_q	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A}, V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu s, V_D \leq 0.67 \cdot V_{DRM}, dv_D/dt = 20 \text{ V}/\mu s$	700			μs

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q_{rr}	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A}, V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu s$	2600		3800	μAs
Reverse recovery current	I_{RM}		50		75	A
Gate turn-on delay time	t_{gd}	$T_{vj} = 25^\circ C, V_D = 0.4 \cdot V_{RM}, I_{FG} = 2 \text{ A}, t_r = 0.5 \mu s$			3	μs

Triggering

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V_{FGM}				12	V
Peak forward gate current	I_{FGM}				10	A
Peak reverse gate voltage	V_{RGM}				10	V
Average gate power loss	$P_{G(AV)}$	see Fig. 9				W

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate-trigger voltage	V_{GT}	$T_{vj} = 25^\circ C$			2.6	V
Gate-trigger current	I_{GT}	$T_{vj} = 25^\circ C$			400	mA
Gate non-trigger voltage	V_{GD}	$V_D = 0.4 \times V_{DRM}, T_{vjmax} = 125^\circ C$	0.3			V
Gate non-trigger current	I_{GD}	$V_D = 0.4 \times V_{DRM}, T_{vjmax} = 125^\circ C$	10			mA

Thermal

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T_{vj}				125	°C
Storage temperature range	T_{stg}		-40		140	°C

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	$R_{th(j-c)}$	Double-side cooled $F_m = 45...60$ kN			10	K/kW
	$R_{th(j-c)A}$	Anode-side cooled $F_m = 45...60$ kN			20	K/kW
	$R_{th(j-c)C}$	Cathode-side cooled $F_m = 45...60$ kN			20	K/kW
Thermal resistance case to heatsink	$R_{th(c-h)}$	Double-side cooled $F_m = 45...60$ kN			2	K/kW
	$R_{th(c-h)}$	Single-side cooled $F_m = 45...60$ kN			4	K/kW

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R_i (K/kW)	6.520	1.550	1.670	0.490
τ_i (s)	0.4562	0.0792	0.0088	0.0037

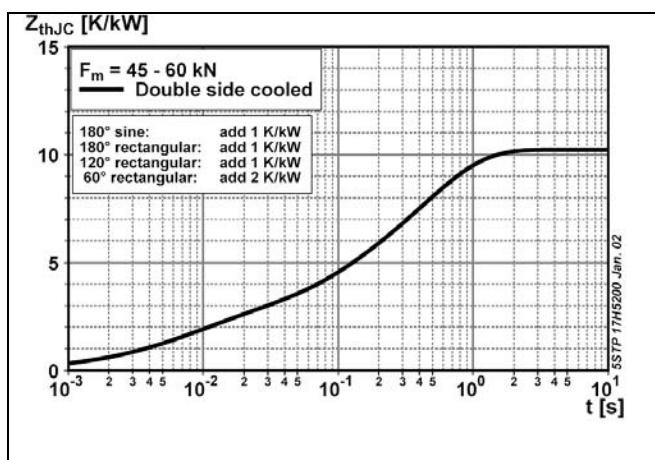


Fig. 1 Transient thermal impedance (junction-to-case) vs. time

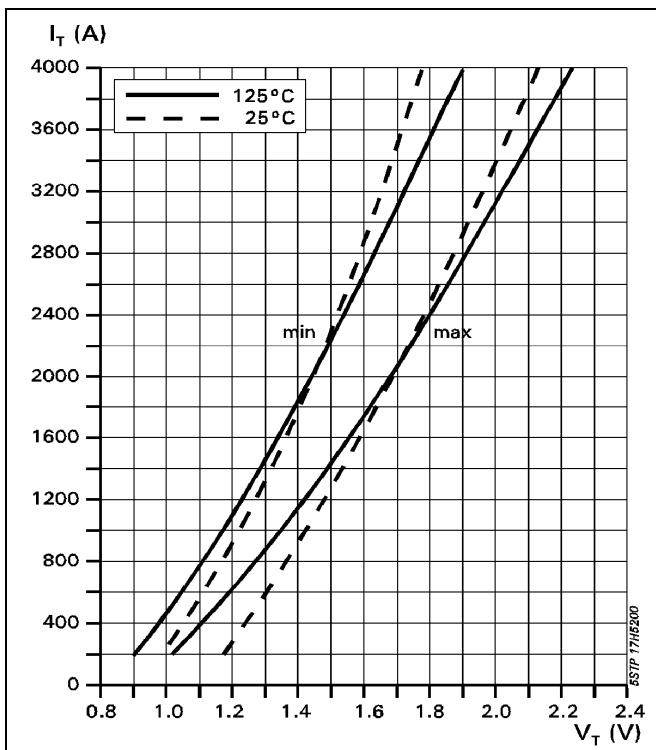


Fig. 2 On-state voltage characteristics

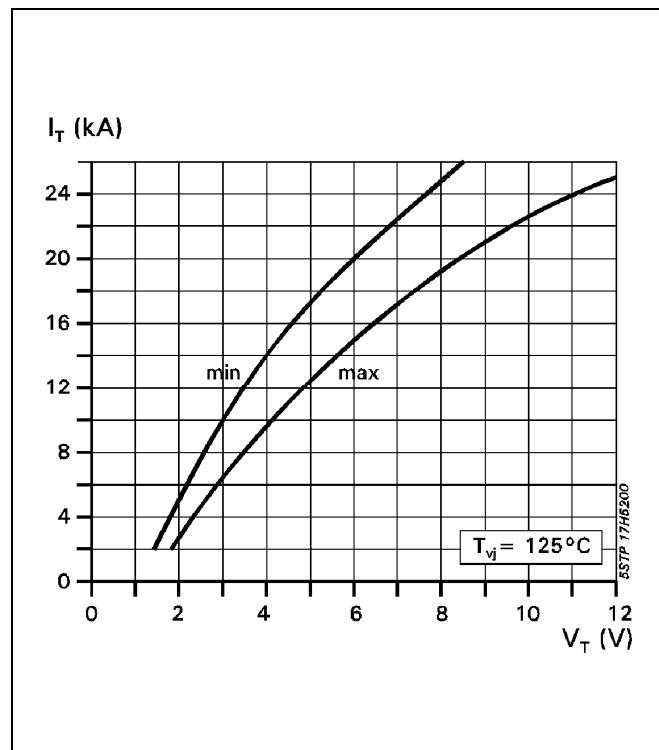
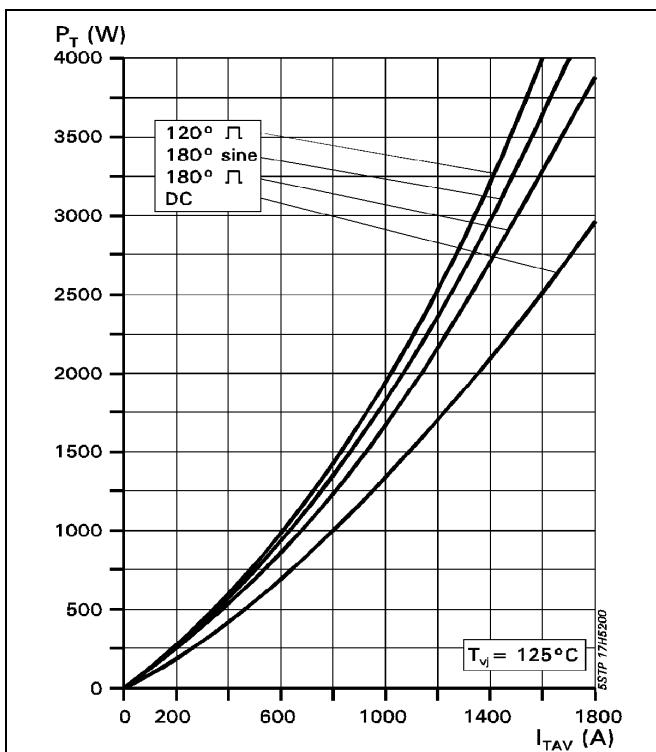
Fig. 3 On-state characteristics,
 $T_j = 125^\circ\text{C}$, 10ms half sine

Fig. 4 On-state power dissipation vs. mean on-state current, turn-on losses excluded

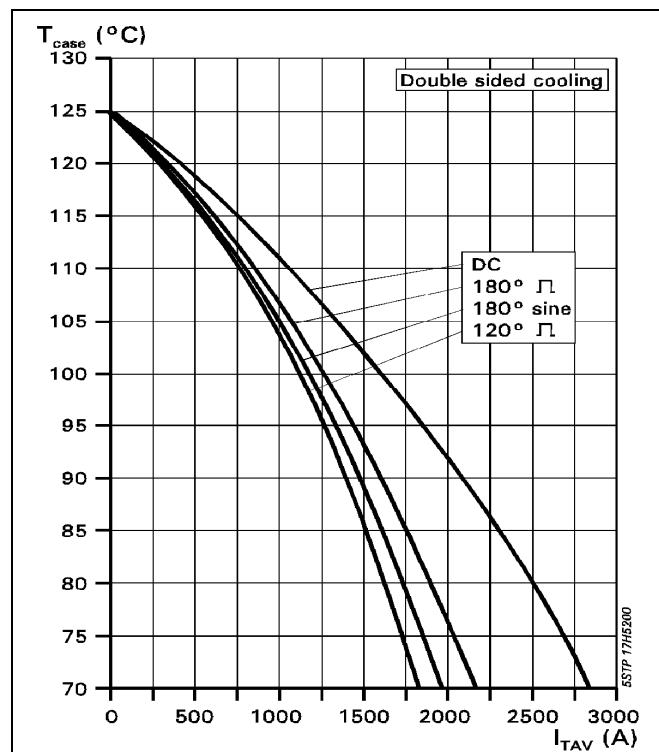


Fig. 5 Max. permissible case temperature vs. mean on-state current, switching losses ignored

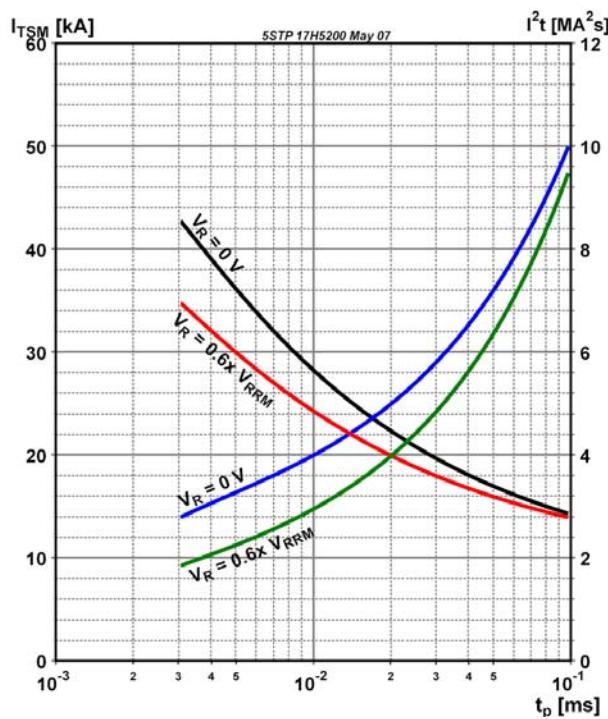


Fig. 6 Surge on-state current vs. pulse length, half-sine wave

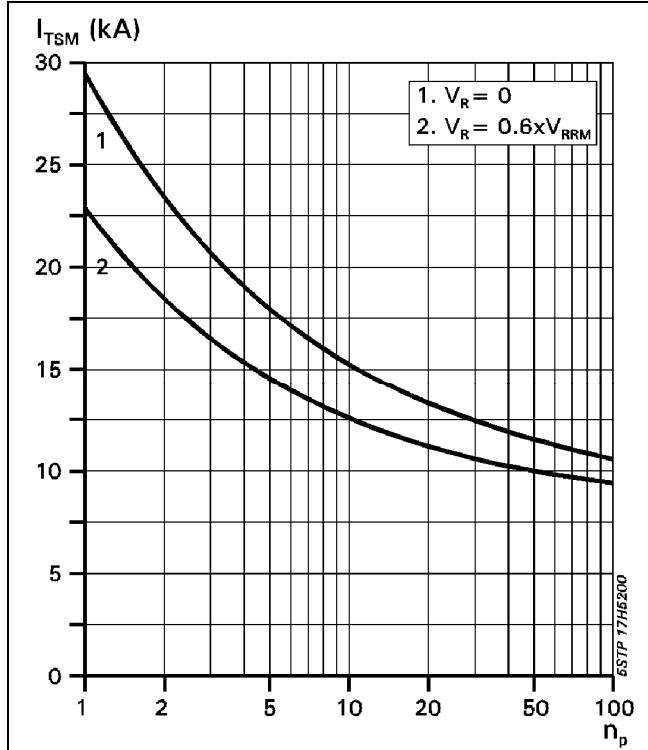


Fig. 7 Surge on-state current vs. number of pulses, half-sine wave, 10 ms, 50Hz

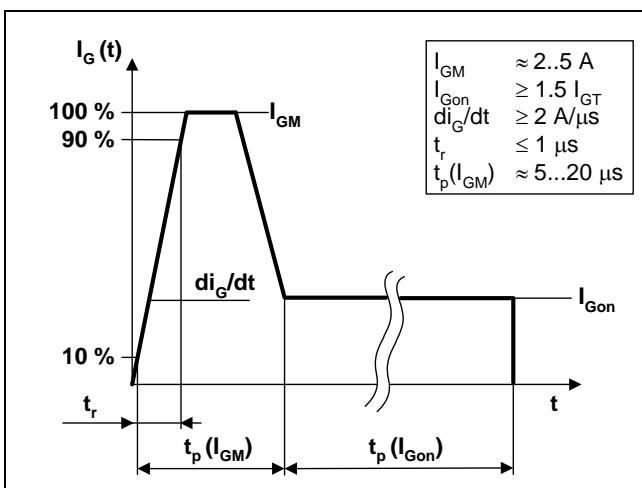


Fig. 8 Recommended gate current waveform

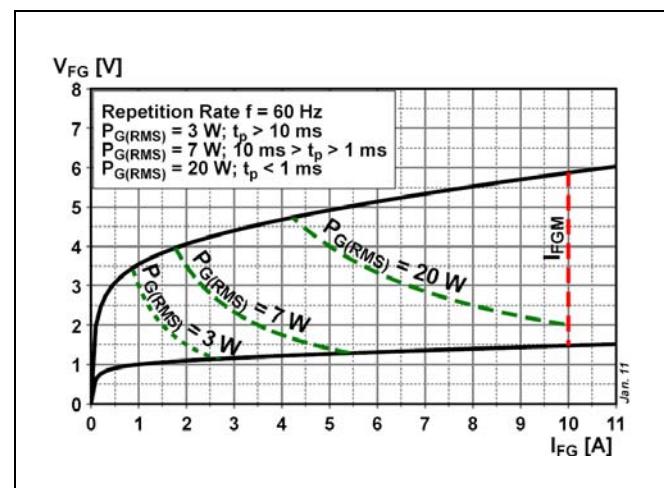


Fig. 9 Max. peak gate power loss

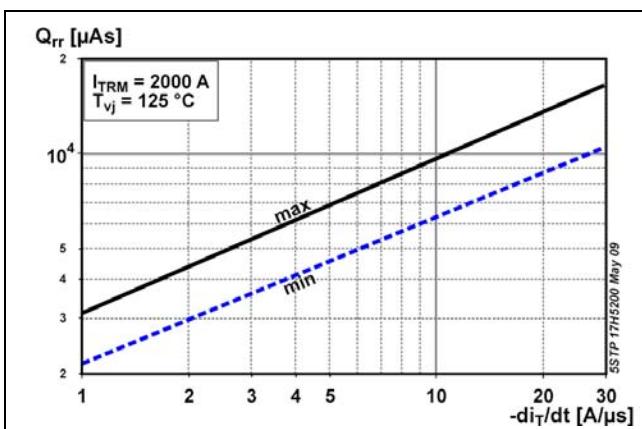


Fig. 10 Reverse recovery charge vs. decay rate of on-state current

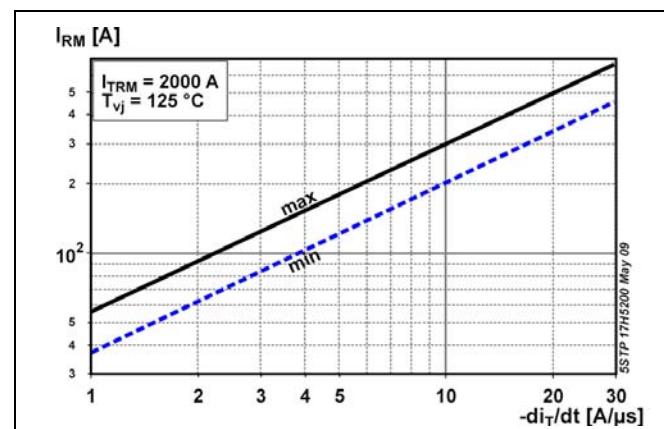
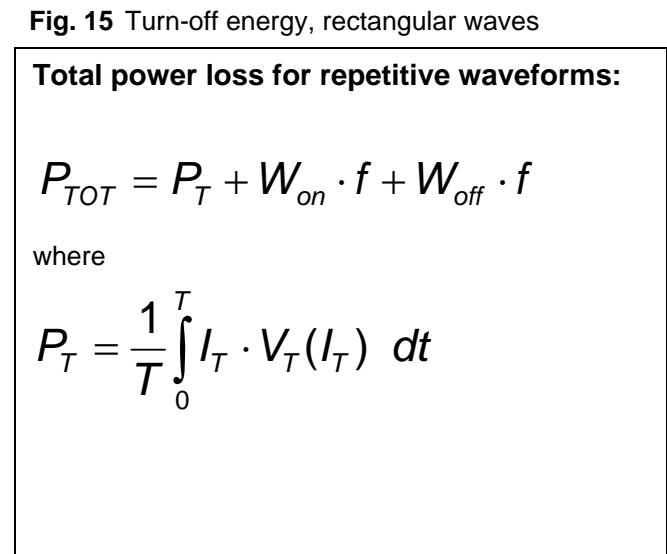
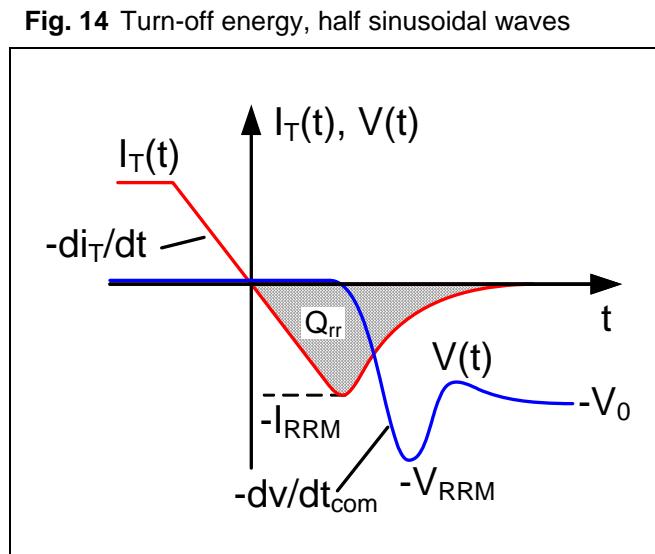
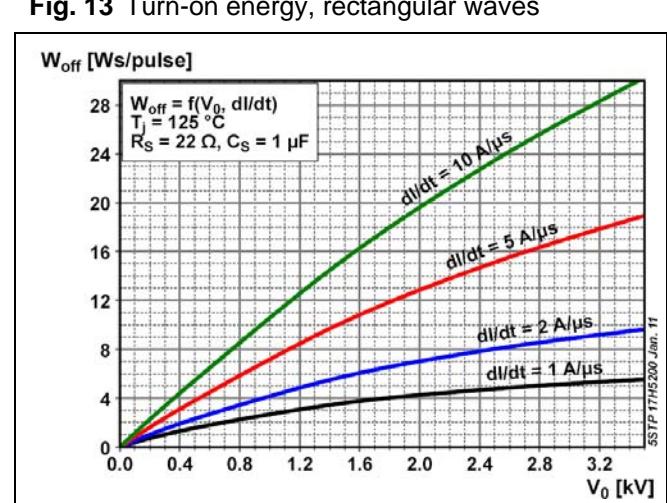
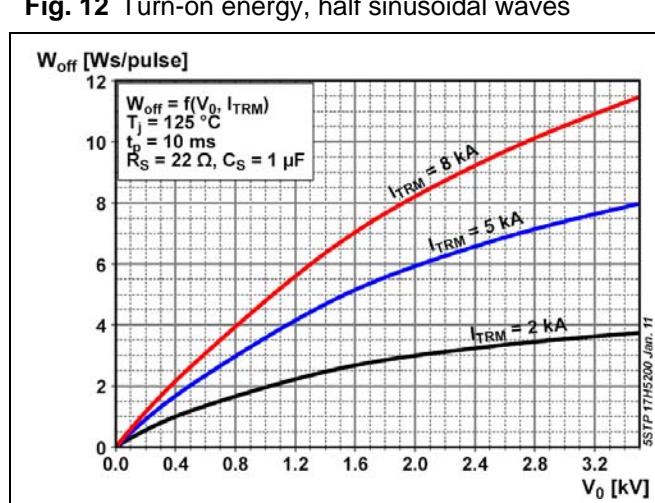
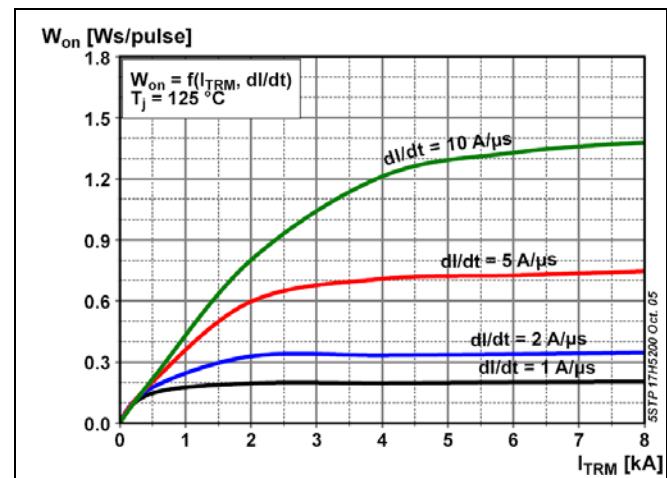
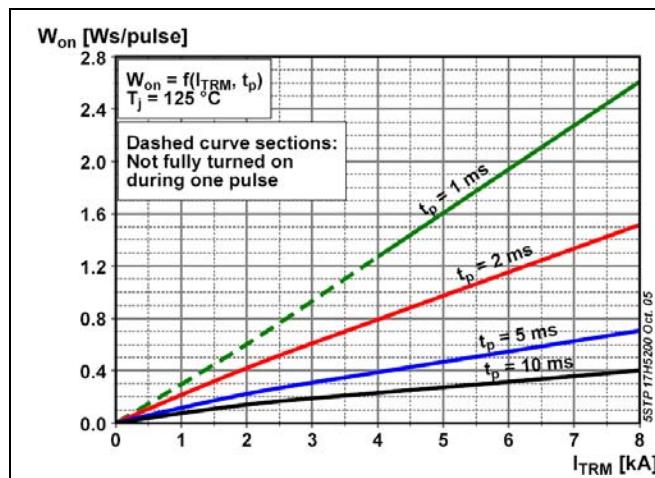


Fig. 11 Peak reverse recovery current vs. decay rate of on-state current

Turn-on and Turn-off losses



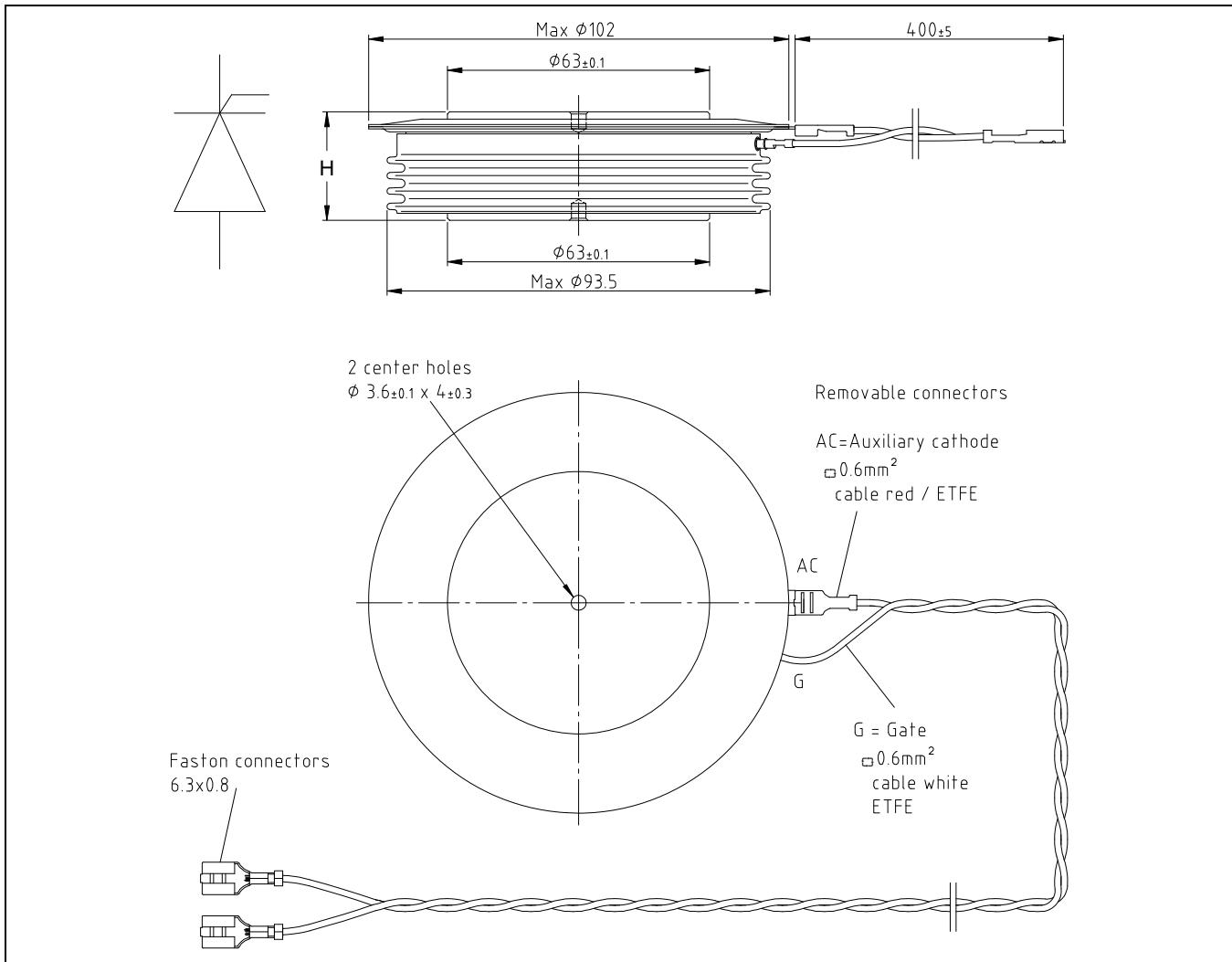


Fig. 18 Device Outline Drawing

Related documents:

- | | |
|-----------|---|
| 5SYA 2020 | Design of RC-Snubber for Phase Control Applications |
| 5SYA 2049 | Voltage definitions for phase control thyristors and diodes |
| 5SYA 2051 | Voltage ratings of high power semiconductors |
| 5SYA 2034 | Gate-Drive Recommendations for PCT's |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors |
| 5SJK 9104 | Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE available on request, please contact factory |
| 5SJK 9105 | Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION available on request, please contact factory |

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**ABB Switzerland Ltd
Semiconductors**
Fabrikstrasse 3
CH-5600 Lenzburg, Switzerland

Doc. No. 5SYA1049-04 Jan. 11

Telephone +41 (0)58 586 1419
Fax +41 (0)58 586 1306
Email abbsem@ch.abb.com
Internet www.abb.com/semiconductors